TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

TCR13AGADJ

1.3 A CMOS Ultra Low Drop-Out Regulator

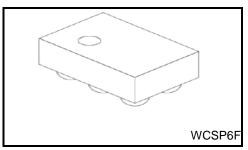
The TCR13AGADJ is CMOS single-output voltage regulator with an on/off control input, featuring Ultra low dropout voltage, low inrush current and fast load transient response.

This voltage regulator is available in output voltage adjustable type from 0.55 V to 3.6 V and capable of driving up to 1.3 A.

Other features include Over-current protection, Over-temperature protection, Inrush current protection circuit, Under-voltage-lockout function and Auto-discharge function.

The TCR13AGADJ is offered in the ultra-small package WCSP6F (0.8 mm x 1.2 mm, t: 0.33 mm (max))

As small ceramic input and output capacitors can be used with the TCR13AGADJ, this device is ideal for portable applications that require high-density board assembly such as cellular phones.



Weight: 0.61 mg (typ.)

Features

· Low Drop-Out voltage

 V_{IN} - V_{OUT} = 92 mV (typ.) at 0.9 V output, V_{BIAS} = 3.3 V, I_{OUT} = 1.0 A V_{IN} - V_{OUT} = 9.2 mV (typ.) at 0.9 V output, V_{BIAS} = 3.3 V, I_{OUT} = 0.1 A

- Wide range Output Voltage (Adjustable from 0.55 V to 3.6 V)
- Fast load transient response $-100 / +115 \text{ mV (typ.)} @ 0.01 \text{ A} \Leftrightarrow 1 \text{ A, Cout} > 4.7 \mu\text{F}$
- Over-current protection
- Thermal Shutdown function
- Inrush current protection circuit
- Under-voltage-lockout function
- · Soft start function
- Auto-discharge function
- Pull down connection between CONTROL and GND
- Ultra Small package WCSP6F (0.8 mm x 1.2 mm, t: 0.33 mm (max))
- Stable with over 4.7 μF Input capacitor, 1.0 μF Bias capacitor and 4.7 μF output ceramic capacitor

Notice

This device is sensitive to electrostatic discharge.

Please ensure equipment and tools are adequately earthed when handling.



Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Bias voltage	V _{BIAS}	6.0	V
Input voltage	VIN	6.0	V
Control voltage	VcT	-0.3 to 6.0	V
Adjustable voltage	V _{ADJ}	-0.3 to 6.0	V
Output voltage	Vout	-0.3 to $V_{IN} + 0.3 \le 6.0$	V
Power dissipation	PD	1.9 (Note 1)	W
Junction temperature	Tj	150	°C
Storage temperature range	T _{stg}	-55 to 150	°C

Note:

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Rating at mounting on a board

(Glass epoxy board dimension: 40 mm x 40 mm, 4 layer Metal pattern ratio: approximately 70% each layer)

Operating Ranges

Characteristics	Symbol	Rating		Unit
Diag voltage	\/	V _{OUT} ≤ 1.1 V, I _{OUT} = 1 mA	2.5 to 5.5	V
Bias voltage	VBIAS	V _{OUT} > 1.1 V, I _{OUT} = 1 mA	V _{OUT} + 1.4 V to 5.5	
Input voltage	VIN	V _{OUT} + 0.1 V to V _{BIAS} (Note 2)		V
Control voltage	Vст	-0.3 to V _{BIAS}		V
Output voltage	Vout	0.55 to 3.6 (Note 3)		V
Output current	lout	1.3 (Max) (Note 4)		Α
Operation Temperature	T _{opr}	-40 to 85		°C
COUT	Соит	4.7μF ≤		_
CIN	C _{IN}	4.7μF ≤		_
CBIAS	C _{BIAS}	1.0μF ≤		_

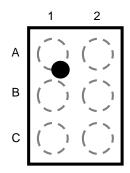
Note 2: $I_{OUT} = 1 \text{ mA}$.

Please refer to Dropout Voltage vs. Output Current(Page 12), and use it within Absolute Maximum Ratings Junction temperature and Operation Temperature Ranges.

Note 3: Output voltage adjustable type. Please refer to Application Note(Page 7).

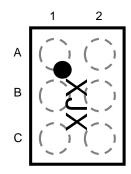
Note 4: Do not operate at or near the maximum recommended current and temperature ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and results in failures not covered by warranty. Maximum recommended DC current specification defined as lifetime average junction temperature of +45°C where max rated DC current = lifetime average current to avoid electro migration.

Pin Assignment (top view)



	1	2
Α	V _{OUT}	V _{IN}
В	V_{ADJ}	CONTROL
С	GND	V_{BIAS}

Top Marking (top view)

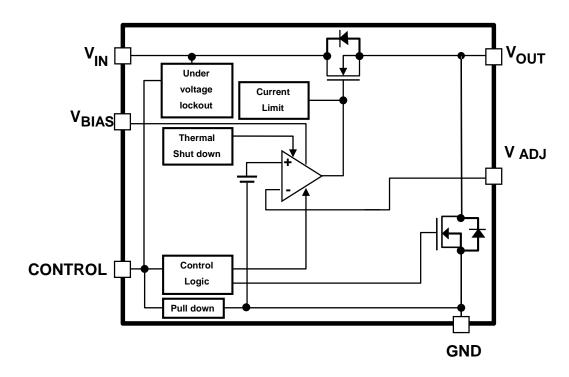


A1: Vout B1: V_{ADJ} C1: GND A2: V_{IN}

B2: CONTROL C2: V_{BIAS}



Block Diagram



Operation Logic table

Output voltage(V)		
V _{OUT}		
0 V (Output discharge)		



Electrical Characteristics

(Unless otherwise specified, Vin = Vout + 0.5 V, lout = 50 mA, Cin = 4.7 μ F, CBIAS = 1.0 μ F, Cout = 4.7 μ F)

Characteristics	Symbol	Test Condition	T _j = 25°C			T _j = -40 to 85°C (Note 7)		Unit
·			Min	Тур.	Max	Min	Max	
	V _{OUT} ≤ 1.1 V, I _{OUT} = 1 mA	2.5	_	5.5	2.5	5.5	V	
Bias voltage	VBIAS	V _{OUT} > 1.1 V, I _{OUT} = 1 mA	V _{OUT} + 1.4 V	_	5.5	V _{OUT} + 1.4 V	5.5	V
Input voltage	VIN	I _{OUT} = 1 mA (Note 5)	V _{OUT} + 0.1 V	_	V _{BIAS}	V _{OUT} + 0.1 V	V _{BIAS}	V
Adjustable voltage	VADJ	_	0.490	0.500	0.510	_	_	V
Line regulation	Reg·line	$V_{OUT} + 0.5 \text{ V} \le V_{IN} \le 5.5 \text{ V},$ $I_{OUT} = 1 \text{ mA}$	_	1	15	_	_	mV
Load regulation	Reg·load	0.01 A ≤ I _{OUT} ≤ 1 A	_	2	_	_	_	mV
Quiescent current	IB	I _{OUT} = 0 mA, V _{BIAS} = 2.5 V (Note 6)	_	56	72	_	92	μА
Stand by ourrant	IBIAS (OFF)	VCT = 0 V	_	0.1	_	_	1	μА
Stand-by current I _{IN(OFF)}		V _{CT} = 0 V (Note 6)	_	0.8	_	_	2	μА
Control pull down current	ICT	_	_	0.1	_	_	_	μΑ
Drop-out voltage	VIN-VOUT	I _{OUT} = 1 A, V _{BIAS} = 3.3 V (Note 7)(Note 9)	_	92	_	_	163	mV
Under voltage lockout	Vuvlo	V _{IN} voltage	_	0.5	_	_	0.65	V
Temperature coefficient	Tcvo	-40°C ≦ T _{opr} ≦ 85°C	_	60	_	_	_	ppm/°C
Output noise voltage	Vno	$V_{BIAS} = 5.5 \text{ V}, V_{IN} = V_{OUT} + 1 \text{ V}, \\ I_{OUT} = 10 \text{ mA}, \\ 10 \text{ Hz} \le f \le 100 \text{ kHz}, Ta = 25^{\circ}\text{C} $ (Note 7)	_	52	-	_	_	μV _{rms}
Pipple rejection ratio	R.R.(V _{IN})	$\begin{split} &V_{BIAS} = 5.5 \text{ V}, V_{IN} = V_{OUT} + 1 \text{ V}, \\ &I_{OUT} = 10 \text{ mA}, \\ &f = 1 \text{ kHz}, V_{IN} \text{ Ripple} = 200 \text{ mV}_{p\text{-}p}, \\ &Ta = 25^{\circ}\text{C} \end{split}$	_	90	_	_	_	dB
Ripple rejection ratio	R.R.(VBIAS)	$\begin{split} &V_{BIAS}=5.5~V,~V_{IN}=V_{OUT}+1~V,\\ &I_{OUT}=10~mA,\\ &f=1~kHz,~V_{BIAS~Ripple}=200~mV_{p-p},\\ &T_{a}=25^{\circ}C~~(Note~7) \end{split}$	_	50		_	_	dB
Load transient response	⊿V _{oυτ}	I _{OUT} =0.01 A → 1 A	_	-100	_	_	_	mV
2000 transiont response		I _{OUT} =1 A → 0.01 A	_	+115	_	_	_	mV
Control voltage (ON)	VCT (ON)	_	1.0	_	5.5	1.0	5.5	V
Control voltage (OFF)	VCT (OFF)	_	0	_	0.4	0	0.4	V
Output discharge on resistance	R _{SD}	_	_	20	_	_	_	Ω

- Note 5: Please refer to Dropout Voltage vs. Output Current (Page 12), and use it within Absolute Maximum Ratings Junction temperature and Operation Temperature Ranges.
- Note 6: This parameter is tested at VOUT = 0.9 V.
 - Control pull down current and external resistors current not included in this parameter.
- Note 7: This parameter is tested at VOUT = 0.9 V.
- Note 8: This parameter is guaranteed by design.
- Note 9: VIN VOUT = VIN1 (VOUT1 100 mV)
 - VOUT1 is the output voltage when VIN = VOUT + 0.5 V.
 - VIN1 is the input voltage at which the output voltage becomes 100 mV drop of VOUT1 after gradually decreasing the input voltage

ton toff Characteristics (Ta = 25°C)

Vou**T** = **1.0 V**

Characteristics	Symbol	Test Condition (Figure 1)	Min	Тур.	Max	Unit
Turn on delay	ton	$\begin{split} &V_{\text{IN}} = 1.235 \text{ V , } V_{\text{BIAS}} = 3.3 \text{ V , } I_{\text{OUT}} = \text{No Load} \\ &C_{\text{IN}} = 4.7 \mu\text{F, } C_{\text{BIAS}} = 1.0 \mu\text{F, } C_{\text{OUT}} = 4.7 \mu\text{F} \end{split}$	_	135	_	μS
Turn off delay	tOFF	$\begin{split} &V_{\text{IN}} = 1.235 \text{ V , } V_{\text{BIAS}} = 3.3 \text{ V , } I_{\text{OUT}} = \text{No Load} \\ &C_{\text{IN}} = 4.7 \mu\text{F, } C_{\text{BIAS}} = 1.0 \mu\text{F, } C_{\text{OUT}} = 4.7 \mu\text{F} \end{split}$	_	230	_	μS

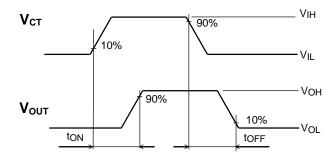
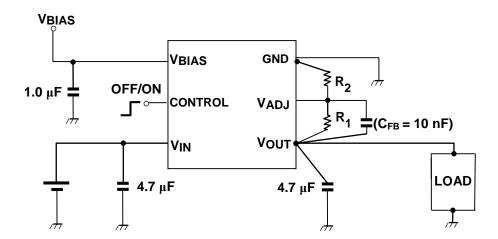


Figure 1 ton, toff Waveforms



Application Note

1. Recommended Application Circuit



The figure above shows the recommended configuration for using a Low-Dropout regulator. Insert a capacitor at VIN, VOUT and VBIAS pins for stable input/output operation. (Ceramic capacitors can be used).

Connect a capacitor with a capacitance value as much as 4.7 μ F or more between VIN and GND pin and 1.0 μ F or more between VBIAS and GND, and as close as possible to the pins. But simple usage of large input capacitance is known to form unwanted LC resonance in combination with input wire inductance. So please check parameter with the actual device and circuit.

C_{FB} is optional capacitance that improve Transient response, Output noise, Oscillation resistance, PSRR and Overshoot. However, it does not necessarily need.

VADJ is the output voltage control pin. Typical VADJ value is 0.5 V. For best performance R1 and R2 should have similar temperature coefficients, otherwise output voltage accuracy will be compromised.

$$V_{OUT} = V_{ADJ} \times \left(1 + \frac{R1}{R2}\right)$$

Reference resistance table

This is reference data. Please check parameter with the actual device and circuit.

Output voltage (typ.)	R1	R2
0.6 V	4 kΩ	20 kΩ
0.7 V	8 kΩ	20 kΩ
0.8 V	12 kΩ	20 kΩ
0.9 V	16 kΩ	20 kΩ
1.0 V	20 kΩ	20 kΩ
1.1 V	24 kΩ	20 kΩ
1.2 V	28 kΩ	20 kΩ
1.3 V	32 kΩ	20 kΩ
1.8 V	52 kΩ	20 kΩ
3.6 V	124 kΩ	20 kΩ

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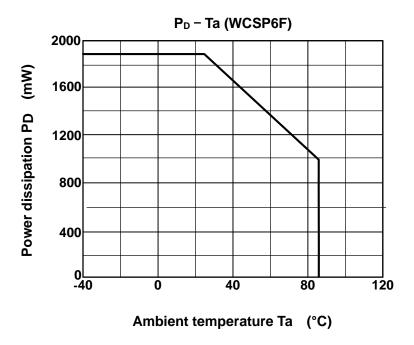
2. Power Dissipation

Board-mounted power dissipation ratings for TCR13AGADJ is available in the Absolute Maximum Ratings table. Power dissipation is measured on the board condition shown below.

[The Board Condition]

Board material: Glass epoxy (FR4)

Board dimension: 40 mm x 40 mm (4 layer), t = 1.8 mm Metal pattern ratio: approximately 70% each layer,



Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc. and applying the appropriate derating for allowable power dissipation during operation.

Attention in Use

Capacitors(Output, Input, and Bias Capacitor)

Ceramic capacitors can be used for these devices. However, because of the type of the capacitors, there might be unexpected thermal features. Please consider application condition for selecting capacitors. And Toshiba recommend the ESR of ceramic capacitor is under 1.0 Ω . For stable operation, please use over 4.7 μ F Input capacitor, 1.0 μ F Bias capacitor and 4.7 μ F output ceramic capacitor.

Mounting

The long distance between IC and each capacitor might affect phase assurance by impedance in wire and inductor. For stable power supply, output capacitor need to mount near IC as much as possible. Also VIN and GND pattern need to be large and make the wire impedance small as possible.

Permissible Loss

Please have enough design patterns for expected maximum permissible loss. And under consideration of surrounding temperature, input voltage, and output current etc, we recommend proper dissipation ratings for maximum permissible loss; in general maximum dissipation rating is 70 to 80 percent.

Over current Protection and Thermal shut down function

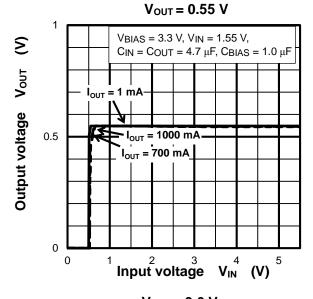
Over current protection and Thermal shut down function are designed in these products, but these are not designed to constantly ensure the suppression of the device within operation limits. Depending on the condition during actual usage, it could affect the electrical characteristic specification and reliability. Also note that if output pins and GND pins are not completely shorted out, these products might be break down.

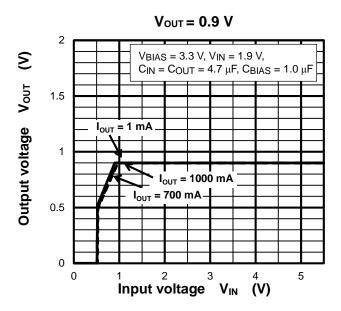
When using these products, please read through and understand the concept of dissipation for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommend inserting failsafe system into the design.

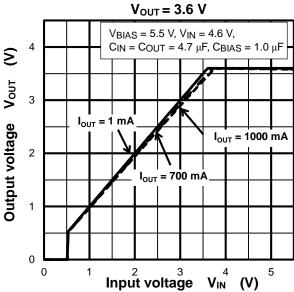
Adjustable output voltage type

TCR13AGADJ is adjustable output voltage type. VADJ is the output voltage control pin, please refer to recommended application circuit and reference resistance table. Please select the tolerance of the resistance value in accordance by the system. In addition, please assemble R1 and R2 to minimize common impedance. For VADJ assembly, please design PCB pattern as short as possible to avoid noise effect.

Output Voltage vs. Input Voltage

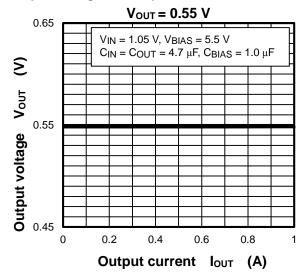


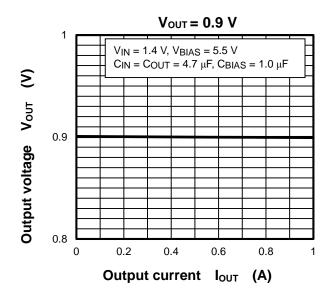


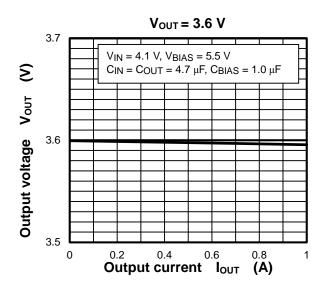


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Output Voltage vs. Output Current

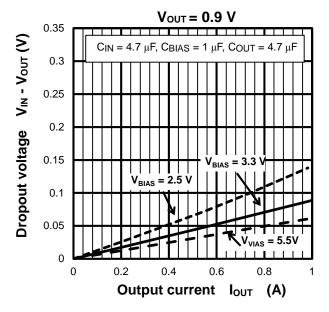


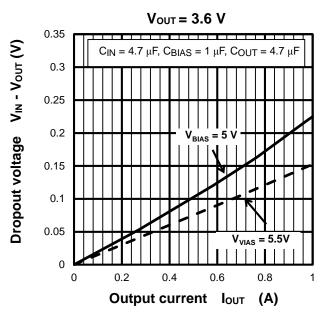




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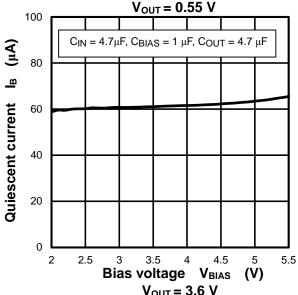
Dropout Voltage vs. Output Current

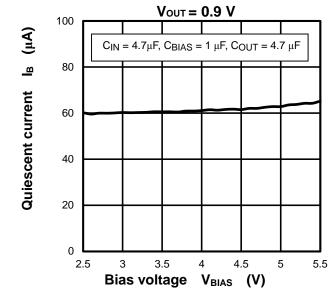


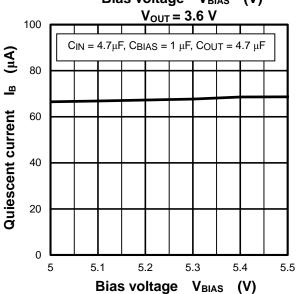


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Quiescent Current vs. Input Voltage

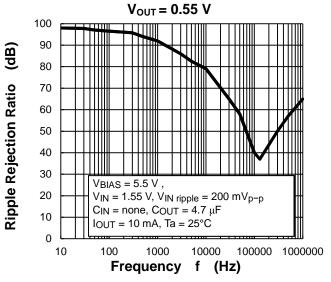


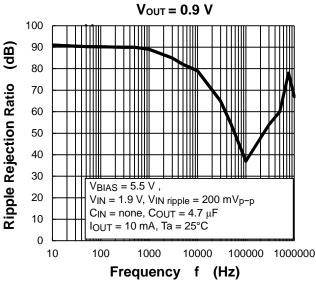


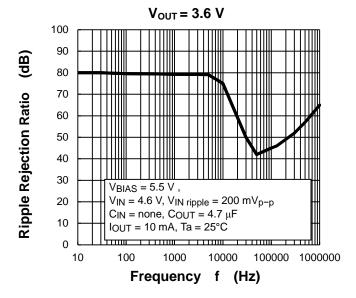


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Ripple Rejection Ratio vs. Frequency

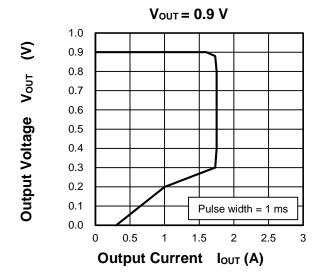


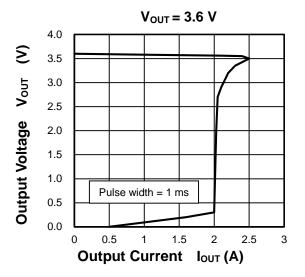




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Output Voltage vs. Output Current (Simulation data)





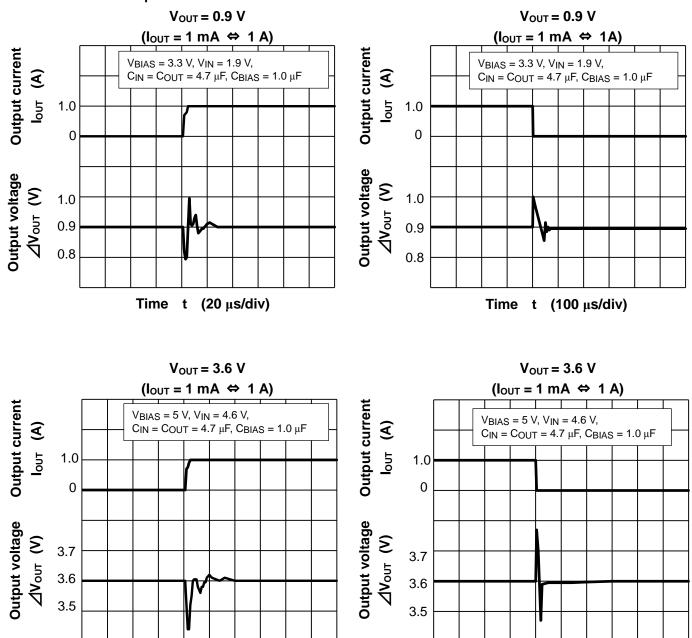
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Load Transient Response

Time

t (20 μs/div)

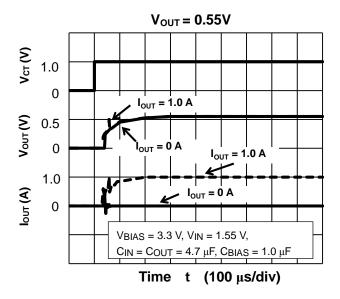


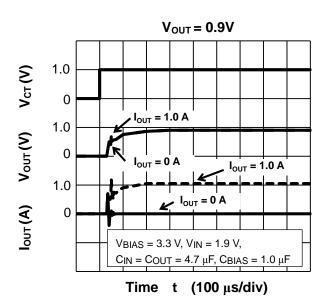
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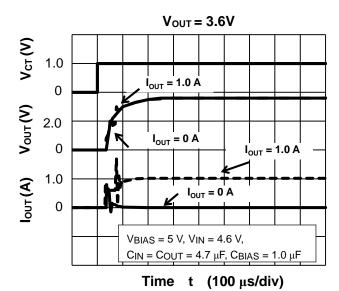
Time t (100 μ s/div)

ton Response

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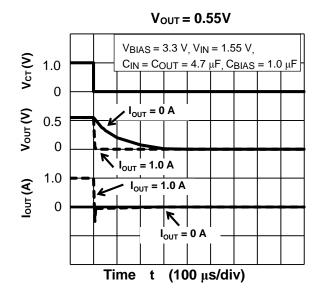


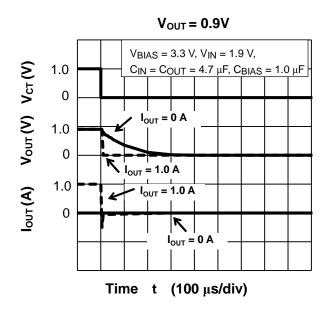


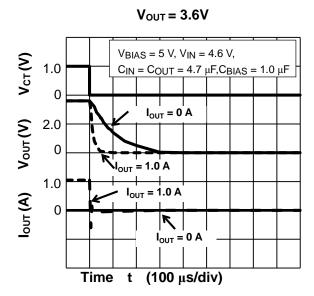


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toff Response



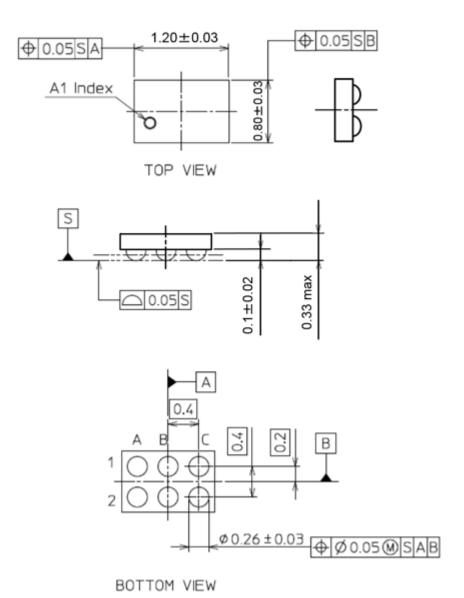




Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

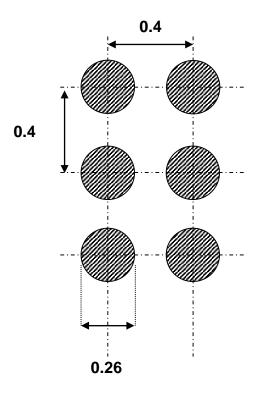
WCSP6F Unit: mm



Weight: 0.61 mg (typ.)

Land pattern dimensions for reference only

WCSP6F



Unit: mm

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